

# **PRODUCT SPECIFICATION**

## MONO LCD MODULE MODEL: G1206B5SGW6B-J1 Ver:1.1

- < <>> Preliminary Specification
- < <> Finally Specification

CUSTOMER'S APPROVAL								
CUSTOMER :								
SIGNATURE:	DATE:							

APPROVED	PM	PD	PREPARED
BY	REVIEWED	REVIEWED	BY
	Filt fan	练深	邱信隆

Revision Status				
Version	Revise Date	Page	Content	Modified By
Ver. 1. 0	2015.04.28		First Issued	
Ver. 1. 1	2015.06.18	6	Add DC/DC circuit	
l				

## **Table of Contents**

No.	Contents Pag	ge
1. FE/	ATURES	.4
2. MEC	CHANICAL SPECIFICATIONS	.4
3. ELE	CTRICAL SPECIFICATIONS	.4
4. TER	MINAL FUNCTIONS AND BLOCK DIAGRAM	.5
5. TIM	NG CHARACTERISTICS	.6
6. INS <sup>-</sup>	FRUCTION SET	.8
7. QU/	LITY SPECIFICATIONS	10
8. REL	IABILITY1	15
9. HAN	IDLING PRECAUTION	16
10. OL	TLINE DIMENSION	17
11. PA	CKING INSTRUCTION	18

#### Issued Date:2015.06.18 **Doc. No.:** QP-001-027/B0

## 1. Features

The features of LCD are as follows

- \* Display mode : STN/Blue/Transmissive/Negative
- \* Drive IC : AIP31107&AIP31108
- \* Interface Input Data : 8 bit
- \* Driving Method : 1/64Duty, 1/6 Bias
- \* Viewing Direction : 6 O'clock
- \* Backlight
- : LED /White
- \*Sample NO. : G1206B5SGW6B-J1\_01/20150427

## 2. MECHANICAL SPECIFICATIONS

Item	Specification	Unit
Module Size	93(W) x 70(H) x 13max(D)	mm
Number of Dots	128x64 Dots	
Viewing Area	70.2(H) x 38.8(V)	mm
Activity Area	66.52(H)x33.24(V)	mm
Dot Size	0.48(H) x 0.48(V)	mm
Dot Pitch	0.52(H) x0.52(V)	mm

## **3. ELECTRICAL SPECIFICATIONS**

3-1 ABSOLUTR MAZIMUM RATINGS (Ta = 25 °C)

ltem	Symbol	Sta			
item	Symbol	Min.	Тур.	Max.	Unit
Supply Voltage For Logic	Vdd – Vss	0.3	-	7.0	V
Supply voltage	Vee	Vdd-19		VDD+0.3	V
Supply Voltage For LCD Drive	V <sub>LCD</sub>	VEE-0.3	-	Vdd +0.3	V
Input Voltage	Vin	-	-	-	V
Operating Temp.	Тор	-20	-	+70	°C
Storage Temp.	Tst	-30	-	+80	°C

\*. NOTE: The response time will be extremely slow when the operating temperature is around  $-10^{\circ}$ C, and the back ground will become darker at high temperature operating.

#### 3-2 ELECTRICAL CHARACTERISTICS

ltem	Symbol	Test Condition	Min.	Тур.	Max.	Unit
Logic supply Voltage	Vdd – Vss		-	5	-	V
LCD Drive	V <sub>LCD</sub>		7.7	8.0	8.3	V
Input Voltage	V <sub>IH</sub>	Ta = 25 °C	0.7Vdd	-	Vdd	V
input voltage	V <sub>IL</sub>	Vdd=5V ± 10%	0	-	0.3Vdd	V
Output voltage	V <sub>OH</sub>		2.4	-	-	V
Output voltage	V <sub>OL</sub>		-	-	0.4	V
Frame Frequency	f <sub>FLM</sub>		-	78	-	Hz
Current Consumption	I <sub>DD</sub>		-	16.4	-	mA

#### 3-3. BACKLIGHT

ltem	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Current	IF		-	-	120	mA
Reverse Dissipation	PD	Ta = 25 °C		-	264	mW
Reverse Current	IR			-	15	uA

#### **3-3-2. Electrical-optical Characteristics**

Item	Symbol	Condition	Min.		in. Typ.		Max.		Unit				
Forward Current	IF		2	.9	3	.1	3	8.3	mA				
Luminance	lv	lf=80mA Ta = 25 ℃	20	200		200		200		-		-	cd/m <sup>2</sup>
Colour Coordinate	_	1a = 25 C	Х	Y	Х	Y	Х	Y					
	-		0.25	0.25	0.25	0.25	0.31	0.31					

The brightness is measured without LCD panel;

For operation above 25°C, The Ifm Ifp &Pd must be derated, the current derating is -0.36mA/°C for DC drive and -0.86 mA/°C for Pulse drive, the Power dissipation is -0.75mW/°C.

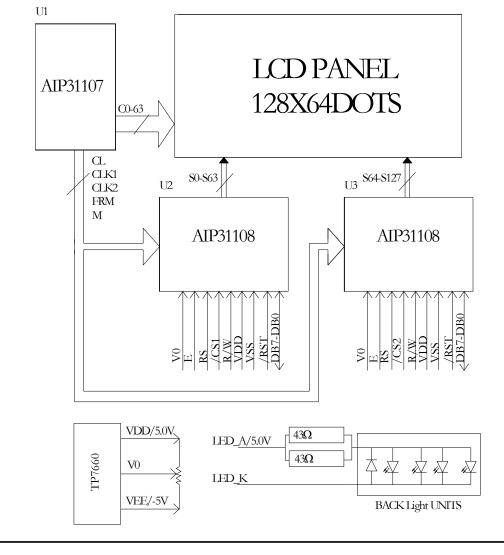
The produt working current must not more than the 60% of the Ifm or Ifp according to the working temperature.

## 4. TERMINAL FUNCTIONS AND BLOCK DIAGRAM

## 4-1. INTERFACE PIN FUNCTION DESCRIPTION

PIN NO.	SYMBOL	FUNCIONS
1	VSS	Ground (0V)
2	VDD	Supply voltage for logical circuit(5V)
3	V0	Supply voltage for LCD driving
4	RS	Select register signal
5	R/W	H: Data Read (LCM to MPU) ; L: Data Write (MPU to LCM)
6	Е	Enable Signal
7~14	DB0~DB7	Data bus line
15	/CS1	Chip Selection Signal for U2
16	/CS2	Chip Selection Signal for U3
17	/RST	Reset (Active "LOW")
18	VEE	Negetive voltage supply pin
19	LED_A	Backlight (+5V)
20	LED_K	Backlight (-)

4-2. BLOCK DIAGRAM



## **5. TIMING CHARACTERISTICS**

Characteristic	Symbol	Min	Тур	Мах	Unit
E Cycle	tC	1000	—		ns
E High Level Width	twn	450	—	—	ns
E Low Level Width	twl	450	—	—	ns
E Rise Time	tR	—		25	ns
E Fall Time	tF	—		25	ns
Address Set-Up Time	tASU	140		—	ns
Address Hold Time	tAH	10	—	—	ns
Data Set-Up Time	tDSU	200	—	—	ns
Data Delay Time	tD	—	—	320	ns
Data Hold Time (Write)	tDHW	10		—	ns
Data Hold Time (Read)	tDHR	20	—	_	ns

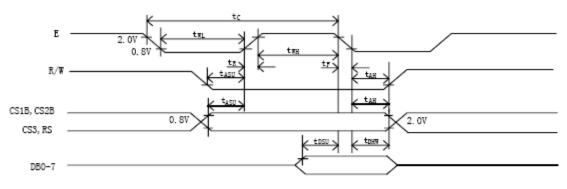


Fig 3. MPU write timing

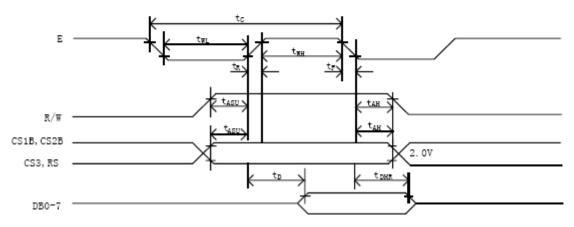


Fig 4. MPU Read timing

## 6. INSTRUCTION SET

The display control instructions control the internal state of the AIP31108. Instruction is received from MPU to AIP31108 for the display control. The following table shows various instructions.

		0	alopiaj	00110101	1110 101	oning .			10401	notraot	
Instruction	RS	R/ W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0	Function
Display ON/OFF	L	L	L	L	н	н	н	н	н	L/H	Controls the display on or off. Internal status and display RAM data is not affected. L:OFF, H:ON
Set Address (Y address)	L	L	L	н	Y addre	ss (0~63	)				Sets the Y address in the Y address counter.
Set Page ( X address)	L	L	Н	L	н	Н	н	Page (	0-7)		Sets the X address at the X address register.
Display Start Line (Z address)	L	L	н	н	Display	start line	Indicates the display data RAM displayed at the top of the screen.				
Status Read	L	Н	busy	L	On/off	reset	L	L	L	L	Read status. BUSY L: Ready H: In operation ON/OFF L: Display ON H: Display OFF RESET L: Normal H: Reset
Write Display Data	н	L	Write D	ata							Writes data (DB0:7) into display data RAM. After writing instruction, Y address is increased by 1 automatically.
Read Display Data	Н	Н	Read D	ata							Reads data (DB0:7) from display data RAM to the data bus.

#### 1. Display On/Off

		••							
RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	0	1	1	1	1	1	D

The display data appears when D is 1 and disappears when D is 0. Though the data is not on the screen with D=0, it remains in the display data RAM. Therefore, you can make it appear by changing D=0 into D=1.

#### 2. Set Address (Y Address)

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	0	0	1	AC5	AC4	AC3	AC2	AC1	AC0

Y address (AC0 ~ AC5) of the display data RAM is set in the Y address counter. An address is set by instruction and increased by 1 automatically by read or write operations of display data.

#### 3. Set Page (X Address)

-										
	RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
Γ	0	0	1	0	1	1	1	AC2	AC1	AC0

X address(AC0 ~ AC2) of the display data RAM is set in the X address register. Writing or reading to or from MPU is executed in this specified page until the next page is set.

#### 4. Display Start Line (Z Address) RS R/W DB7 DB6 DB5 DB4 DB3 DB2 DB1 DB0 0 0 1 1 AC5 AC4 AC3 AC2 AC1 ACO

Z address (AC0 ~ AC5) of the display data RAM is set in the display start line register and displayed at the top of the screen. When the display duty cycle is 1/64 or others(1/32 ~ 1/64), the data of total line number of LCD screen, from the line specified by display start line instruction, is displayed.

#### 5. Status Read

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
0	1	BUSY	0	ON/OFF	RESET	0	0	0	0

BUSY

When BUSY is 1, the Chip is executing internal operation and no instructions are accepted. When BUSY is 0, the Chip is ready to accept any instructions.

ON/OFF

When ON/OFF is 1, the display is on.

When ON/OFF is 0, the display is off.

RESET

When RESET is 1, the system is being initialized. In this condition, no instructions except status read can be accepted.

When RESET is 0, initializing has finished and the system is in the usual operation condition.

#### 6. Write Display Data

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	0	D7	D6	D5	D4	D3	D2	D1	D0

Writes data (D0 ~ D7) into the display data RAM.

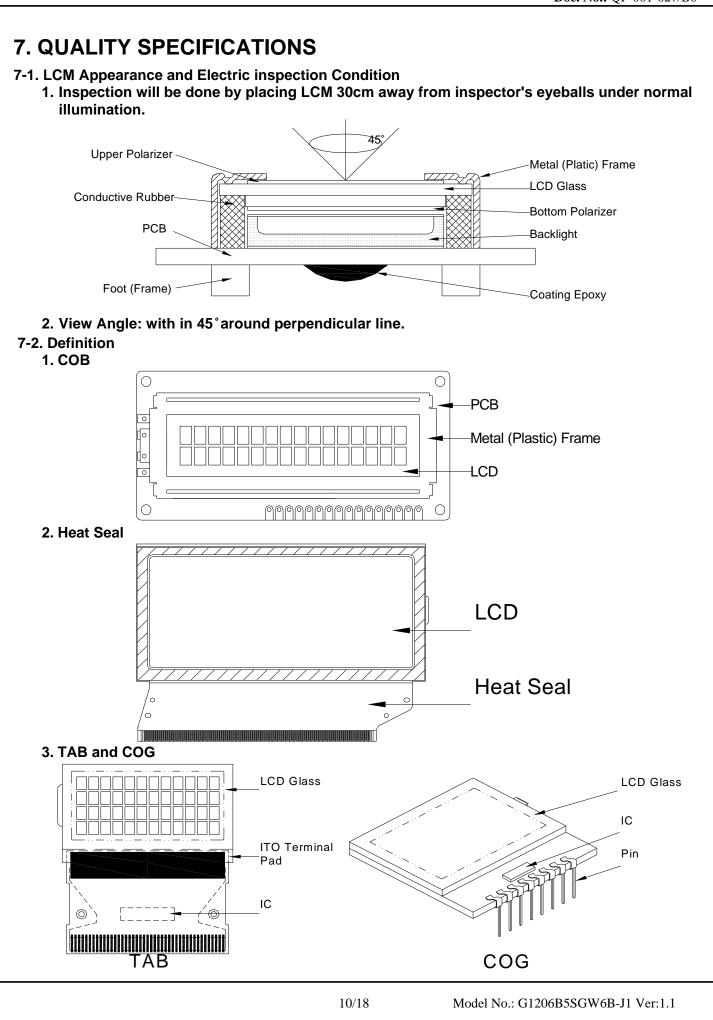
After writing instruction, Y address is increased by 1 automatically.

#### 7. Read Display Data

RS	R/W	DB7	DB6	DB5	DB4	DB3	DB2	DB1	DB0
1	1	D7	D6	D5	D4	D3	D2	D1	D0

Reads data (D0 ~ D7) from the display data RAM.

After reading instruction, Y address is increased by 1 automatically.



#### **Issued Date:**2015.06.18 **Doc. No.:** QP-001-027/B0

# **7-3. Sampling Plan and Acceptance** 1.Sampling Plan

MIL - STD - 105E (  $\parallel$  ) ordinary single inspection is used.

2. Acceptance Major defect: AQL = 0.65% Minor defect: AQL = 1.5%

#### 7-4. Criteria

#### 1.COB

Defect	Inspection Item	Inspection Standards	
Major	PCB copper flakes peeling off	Any copper flake in viewing Area should be greater than 1.0mm <sup>2</sup>	Reject
Major	Height of coating epoxy	Exceed the dimension of drawing	Reject
Major	Void or hole of coating epoxy	Expose bonding wire or IC	Reject
Major	PCB cutting defect	Exceed the dimension of drawing	Reject

#### 2. SMT

Defect	Inspection Item	Inspection Standa	ards
Minor	Component marking not readable		Reject
Minor	Component height	Exceed the dimension Of drawing	Reject
Major	Component solder defect (missing , extra, wrong component or wrong orientation		Reject
Minor	Component position shift x component soldering pad $x$ $\rightarrow$ $x$ $\rightarrow$ $x$ $\rightarrow$ $y$	X < 3/4Z Y > 1/3D	Reject Reject
Minor	Component tilt component D soldering pad	Y > 1/3D	Reject
Minor	Insufficient solder component PAD PCB	<i>θ</i> <u>&lt;</u> 20°	Reject

#### 3. Metal (Plastic) Frame

Defect	Inspection Item	l h	nspection Standa	rds		
Major	Crack / breakage	Any	/where	Reject		
		W	L	Acceptable of Scratch		
		w<0.1mm	Any	Ignore		
		0.1 <u>&lt;</u> w<0.2mm	L <u>&lt;</u> 5.0mm	2		
Minor	Frame Scratch	0.2 <u>&lt;</u> w<0.3mm	L <u>&lt;</u> 3.0mm	1		
		w <u>&gt;</u> 0.3mm	Any	0		
		Note : 1. Above criteria applicable to scratch lines with distance greater than 5mm. 2. Scratch on the back side of frame (not visible) can be ignored.				
				Acceptable of Dents / Pricks		
		⊕ <u>&lt;</u> 1.0mm		2		
	Frame Dent , Prick	1.0<⊕ <u>&lt;</u> 1.5mm		1		
Minor	$\Phi = \frac{L + W}{2}$	1.5r	mm< $\Phi$	0		
	2	Note : 1. Above criteria applicable to any two dents / pricks with distance greater than 5mm 2. Dent / prick on the back side of frame (not visible) can be ignored				
Minor	Frame Deformation	Excee	d the dimension of	drawing		
Minor	Metal Frame Oxidation		Any rust			

#### 4. Flexible Film Connector (FFC)

Defect	Inspection Item	Inspection Standa	rds
Minor	Tilted soldering	Within the angle +5°	Acceptable
Minor	Uneven solder joint /bump		Reject
		Expose the conductive line	Reject
Minor	Hole $\Phi = \frac{L + W}{2}$	$\Phi$ > 1.0mm	Reject
Minor	Position shift $\gamma \xrightarrow{- \frac{1}{2}} \xrightarrow{- \frac{1}{2}$	Y > 1/3D	Reject
Minor		X > 1/2Z	Reject

#### 5. Screw

Defect	Inspection Item	Inspection Standards	
Major	Screw missing/loosen		Reject
Minor	Screw oxidation	Any rust	Reject
Minor	Screw deformation	Difficult to accept screw driver	Reject

### 6. Heatseal 、TCP 、FPC

Defect	Inspection Item	Inspection Standards	
Major	Scratch expose conductive layer		Reject
Minor	HS Hole $\Phi = \frac{L + W}{2}$	<b>⊕&gt; 0.5mm</b>	Reject
Major	Adhesion strength	Less than the specification	Reject
Minor	Position shift $Y \xrightarrow{-\psi} -\psi$	Y > 1/3D	Reject
WIITIO		X > 1/2Z	Reject
Major	Conductive line break		Reject

#### 7. LED Backing Protective Film and Others

Defect	Inspection Item	n Inspection Standards						
Minor		Acceptable number of units						
		⊕ <u>&lt;</u> 0.10mm						
	LED dirty, prick	0.10<⊕ <u>&lt;</u> 0.15mm	2					
		0.15<⊕ <u>&lt;</u> 0.2mm	1					
		⊕>0.2mm	0					
		The distance between any two spots should be $\geq$ 5mm Any spot/dot/void outside of viewing area is acceptable						
Minor	Protective film tilt	Not fully cover LCD Re						
Major	COG coating	Not fully cover ITO circuit	Reject					

#### 8. Electric Inspection

Defect	Inspection Item	Inspection Standards	
Major	Short		Reject
Major	Open		Reject

#### 9. Inspection Specification of LCD

Defect	Insp	Inspection Standards								
Minor		* Glass Scratch	W	W <u>&lt;</u> 0.03		0.0			V>0.05	
		* Polarizer Scratch	L		L	<5		L<3		Any
	Linear Defect	* Fiber and Linear	ACC. NO.	1				1		Reject
		material	Note	L is th	L is the length and W is the width of the de					
Minor	Black Spot and Polarizer Pricked	* Foreign material		Φ <u>&lt;</u> 0				i 0.15<Φ <u>&lt;</u> 0.2		<b>Φ&gt;0.2</b>
		between glass and polarizer or glass		3EA 100m		2		1		0
		and glass * Polarizer hole or protuberance by external force	Note	⊕ is t	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.					
		* Unobvious	*		Ф <u>&lt;</u> 0.3			0.3<⊕ <u>&lt;</u> 0.5 0.		<b>5</b> <Φ
Minor	White Spot and Bubble in polarizer	transparant foreign material between		3EA	/ 10	00mm <sup>2</sup>		1		0
		glass and glass or glass and polarizer * Air protuberance between polarizer and glass	Note	$\Phi$ is the average diameter of the defect. Distance between two defects > 10mm.						
Minor	Segment Defect		Φ	Φ <u>&lt;</u> 0.	10	0.10<⊅ <u>∢</u>	<u>&lt;</u> 0.20	0.20<⊕ <u>&lt;</u>	<u>&lt;</u> 0.25	Φ> <b>0.2</b>
			ACC. NO.	3EA 100m	./ m²	2	2		1	
				W is more than 1/2 segment width Rejea						Reject
			Note	$\Phi = \frac{L + W}{2}$ Distance between two defect is 10mm						
Minor	Protuberant Segment		Φ	Φ <u>&lt;</u> 0.	10	0.10<⊕ <u>&lt;</u> 0.20		0.20<⊕ <u>&lt;</u> 0.25		Φ> <b>0.2</b>
		w k k k k k k k k k k k k k k k k k k k	w	Glu	е	W <u>&lt;</u> 1/2 W <u>&lt;</u> 0.		W <u>&lt;</u> 1/2 Seg W <u>&lt;</u> 0.2		Ignore
		$\Phi = (L + W) / 2$	ACC. NO.	3EA 100m		2		1		0
Minor	Assembly Mis-alignment	N A	1. Segment							
			E	B B <u>&lt;</u>		<u>&lt;</u> 0.4mm 0.4<		B <u>&lt;</u> 1.0mm B>1		.0mm
			B-	B-A B		A<1/2B	B-,	B-A<0.2 B-A		<0.25
				udge Acceptable Acceptable			Acceptable			
			2. Dot	2. Dot Matrix						
			Deformation>2° Re						Reject	
Minor	Stain on LCD Panel Surface		Accept when stains can be wiped lightly with a soft cloth or a similar one. Otherwise, judged according to the above items: "Black spot" and "White Spot"							

#### 8. RELIABILITY Condition Quantity Criteria No Item GB/T2423.2 1 High Temperature Operating 70°C, 96Hrs 2 -2008GB/T2423.1 2 -20°C, 96Hrs 2 Low Temperature Operating -2008 GB/T2423.3 3 **High Humidity** 2 50°C, 90%RH, 96Hrs -2006 GB/T2423.2 2 4 High Temperature Storage 80°C, 96Hrs -2008 GB/T2423.1 5 2 Low Temperature Storage -30°C, 96Hrs -2008 GB/T2423.2 -20°C, 60min~70°C, 60min, 6 Thermal Cycling Test 2 2 20 cycles. -2012 Frequency range:10Hz~50Hz GB/T5170.1 7 Packing vibration Acceleration of gravity:5G 2 4 X,Y,Z 30 min for each direction. -2009 Air: $\pm$ 8KV 150pF/330 $\Omega$ 5 times GB/T17626. 8 **Electrical Static Discharge** 2 2 Contact: $\pm$ 4KV 150pF/330 $\Omega$ 5 -2006 times Height:80 cm,1 corner, 3 edges, **Drop Test** GB/T2423.8 9 2 (Packaged) -1995 6 surfaces.

Note: 1) Above conditions are suitable for our company standard products.

2) For restrict products, the test conditions listed as above must be revised.

## 9. HANDLING PRECAUTION

(1) Mounting Method

The panel of the LCD Module consists of two thin glass plates with polarizers which easily get damaged since the Module is fixed by utilizing fitting holes in the printed circuit board. Extreme care should be taken when handling the LCD Modules.

(2) Caution of LCD handling & cleaning

When cleaning the display surface, use soft cloth with solvent (recommended below) and wipe lightly.

- Isopropyl alcohol
- Ethyl alcohol
- Trichloro trifloro thane

Do not wipe the display surface with dry or hard materials that will damage the polarizer surface. Do not use the following solvent:

- Water- Ketone- Aromatics
- (3) Caution against static charge

The LCD Module use C-MOS LSI drivers, so we recommend that you connect any unused input terminal to VDD or VSS, do not input any signals before power is turned on. And ground your body, Work/assembly table. And assembly equipment to protect against static electricity.

- (4) Packaging
  - Modules use LCD elements, and must be treated as such. Avoid intense shock and falls from a height.
  - To prevent modules from degradation. Do not operate or store them exposed directly to sunshine or high temperature/humidity.
- (5) Caution for operation
  - It is indispensable to drive LCD's within the specified voltage limit since the higher voltage than the limit shorten LCD life. An electrochemical reaction due to direct current causes LCD deterioration, Avoid the use of direct current drive.
  - Response time will be extremely delayed at lower temperature than the operating temperature range and on the other hand at higher temperature LCD's show dark color in them. However those phenomena do not mean malfunction or out of order with LCD's. Which will come back in the specified operating temperature range.
  - If the display area is pushed hard during operation, some font will be abnormally displayed but it resumes normal condition after turning off once.
  - A slight dew depositing on terminals is a cause for electro-chemical reaction resulting in terminal open circuit.
  - Usage under the relative condition of 40°C, 50%RH or less is reequired.

#### (6) Storage

- In the case of storing for a long period of time (for instance.) For years) for the purpose or replacement use, The following ways are recommended.
  - Storage in a polyethylene bag with sealed so as not to enter fresh air outside in it, And with no desiccant.
- Placing in a dark place where neither exposure to direct sunlight nor light is. Keeping temperature in the specified storage temperature range.
- Storing with no touch on polarizer surface by the anything else. (It is recommended to store them as they have been contained in the inner container at the time of delivery)
- (7) Safety
  - It is recommendable to crash damaged or unnecessary LCD into pieces and wash off liquid crystal by using solvents such as acetone and ethanol.
  - Which should be burned up later.
  - When any liquid crystal leaked out of a damaged glass cell comes in contac with your hands, please wash it off well with soap and wate
- (8) Other
  - After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

